- Single-Chip and Single-Supply Interface for IBM PC/AT™ Serial Port
- Meets or Exceeds the Requirements of TIA/EIA-232-F and ITU v.11 Standards
- Operates With 3.3-V or 5-V Supplies
- One Receiver Remains Active During Standby (Wake-up Mode)
- Designed to Operate at 128 kbit/s Over a 3-m Cable
- Low Standby Current . . . 5 μA Max
- ESD Protection on RS-232 Pins Meets or Exceeds 4 kV (HBM) and 1.5 kV (HBM) on All Pins Per MIL-STD-883, Method 3015
- External Capacitors . . . 0.1 μF  $(V_{CC} = 3.3 V \dots Five External Capacitors)$ (V<sub>CC</sub> = 5 V . . . Four External Capacitors)
- Accepts 5-V Logic Input With 3.3-V Supply
- Applications
  - RS-232 Interface
  - Battery-Powered Systems, PDAs
  - Notebook, Laptop, and Palmtop PCs
  - External Modems and Hand-Held **Terminals**
- Packaged in Shrink Small-Outline Package

#### (TOP VIEW) $V_{DD}$ 28 ∏ C3+ C2+ [ GND 2 27 V<sub>CC</sub> **□** 3 26 C3-C2- $\Pi$ 25 VSS EN [ 5 24 ∏ C1– С1+ П 23 STBY 6 DIN1 22 DOUT1 21 DOUT2 DIN2 8 DIN3 [ 20 DOUT3 9 ROUT1 10 19 RIN1 ROUT2 □ RIN2 11 18 ROUT3 ∏ RIN3 12 17 16 RIN4 ROUT4 13 ROUT5 15 RIN5

DB PACKAGE<sup>†</sup>

<sup>†</sup>The DB package is only available in left-ended tape and (order part number SN75LV4737ADBR).

#### description

The SN75LV4737A<sup>‡</sup> consists of three line drivers, five line receivers, and a charge-pump circuit. It provides the electrical interface between an asynchronous communication controller and the serial-port connector, and meets the requirements of TIA/EIA-232-F. This combination of drivers and receivers matches those needed for the typical serial port used in an IBM PC/AT or compatibles. The charge pump and five small external capacitors allow operation from a single 3.3-V supply, and four capacitors allow operation from a 5-V supply.

The device has flexible control options for power management when the serial port is inactive. A common disable for all of the drivers and receivers is provided with the active-high STBY input. The active-low EN input is an enable for one receiver to implement a wake-up feature for the serial port. All the logic inputs can accept signals from controllers operating from a 5-V supply, even though the SN75LV4737A is operating from 3.3 V.

The SN75LV4737A is characterized for operation over the temperature range of 0°C to 70°C.



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‡ Patent-pending design

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### **Function Tables**

#### **EACH DRIVER**

INP	UTS	OUTPUT
DIN	STBY	DOUT
Х	Н	Z
L	L	Н
Н	L	L
Open	L	L

H = high level, L = low level, X = irrelevant, Z = high impedance

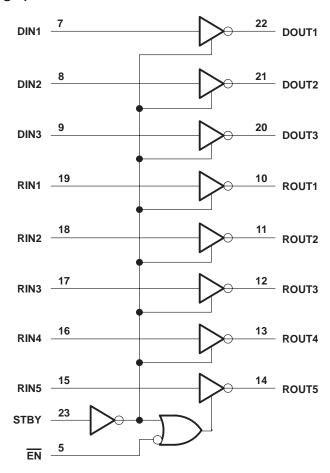
#### **EACH RECEIVER**

		INPUTS		OUTPUTS				
STBY	EN	RIN5	RIN1-RIN4	ROUT5	ROUT1-ROUT4			
Н	Н	Х	Х	Z	Z			
Н	L	Н	X	L	Z			
Н	L	L	X	н	Z			
L	Χ	L	L	Н	Н			
L	Χ	Н	Н	L	L			

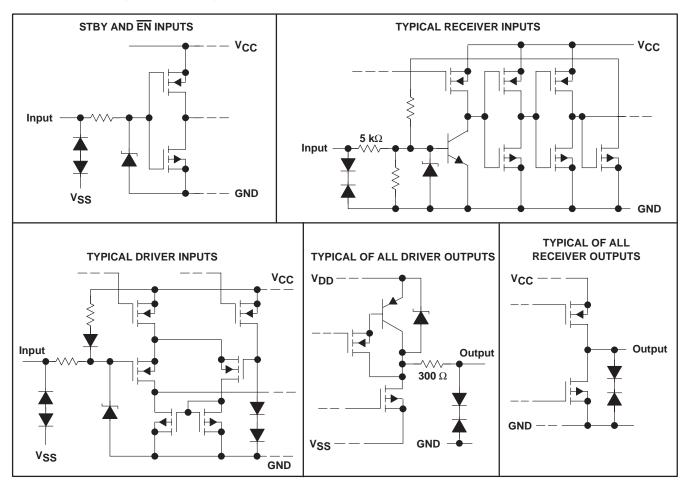
H = high level, L = low level, X = irrelevant, Z = high impedance



## logic diagram (positive logic)



### schematics of inputs and outputs



## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V <sub>CC</sub>	
Positive output supply voltage, V <sub>DD</sub> (see Note 1)	
Negative output supply voltage, V <sub>SS</sub>	–15 V
Input voltage range, V <sub>I</sub> : Driver	–3 V to 7 V
Receiver	
Output voltage range, VO: Driver	$V_{SS} - 0.3 \text{ V to } V_{DD} + 0.3 \text{ V}$
Receiver	–0.3 V to 7 V
Package thermal impedance, $\theta_{JA}$ (see Note 2)	62°C/W
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltages are with respect to network GND.
  - 2. The package thermal impedance is calculated in accordance with JESD 51.



## SN75LV4737A 3.3-V/5-V MULTICHANNEL RS-232 LINE DRIVER/RECEIVER

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## recommended operating conditions

				MIN	NOM	MAX	UNIT
Vac	Supply voltage		V <sub>CC</sub> = 3.3 V	3	3.3	3.6	V
Vcc	Supply voltage		V <sub>CC</sub> = 5 V	4.5	5	5.5	V
		DIN, EN, STBY	V <sub>CC</sub> = 3.3 V	2			
VIH	Driver high-level input voltage	DIN	V 5 V	2			V
		EN, STBY	V <sub>CC</sub> = 5 V	2.5			
VIL	Driver low-level input voltage	DIN, EN, STBY			0.8	V	
٧ <sub>I</sub>	Receiver input voltage					±30	V
	External capacitor	3.3-V operation (C1, C2, C3, C4, C5), 5-V operation (C1, C3, C4, C5), See Note 3 and Figures 6 and 7					μF
T <sub>A</sub>	Operating free-air temperature	•		0		70	°C

NOTE 3: C2 is needed only for 3.3-V operation.

## electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (see Figures 6 and 7) (unless otherwise noted)

	PARAMETER	TEST	CONDITIONS	V <sub>CC</sub> = 3.3 V			V <sub>CC</sub> = 5 V			UNIT
	PARAMETER	IEST	CONDITIONS	MIN	TYP†	MAX	MIN	TYP <sup>†</sup>	MAX	Olari
$V_{DD}$	Positive supply voltage	No load	8	10		7	8.7		V	
Vss	Negative supply voltage	No load		-9.5	-7		-8	-6	V	
II	Input current (EN, STBY)	See Notes 4 a			±2			±2	μΑ	
	Supply current		STBY at GND, EN at V <sub>CC</sub> or GND	8.4	10	18	10	12	20.7	mA
ICC	Supply current (standby mode) (see Note 4)	No load, Inputs open	EN, STBY at V <sub>CC</sub>			5			5	^
	Supply current (wake-up mode) (see Note 5)		EN at GND, STBY at V <sub>CC</sub>			10			10	μΑ

† All typical values are at  $V_{CC} = 3.3 \text{ V}$  or  $V_{CC} = 5 \text{ V}$ , and  $T_A = 25^{\circ}\text{C}$ . NOTES: 4. When standby mode is not used, STBY input must be taken low.



<sup>5.</sup> When wake-up mode is not used,  $\overline{\mathsf{EN}}$  input must be taken high.

#### **DRIVER SECTION**

## electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

	PARAMETER	TEST CONDITION	MIN	TYP†	MAX	UNIT	
Vон	High-level output voltage	$R_L = 3 \text{ k}\Omega$		5.5	7		V
VOL	Low-level output voltage	$R_L = 3 \text{ k}\Omega$			-6	-5	V
lн	High-level input current	VI = VCC				1	μΑ
I <sub>I</sub> L	Low-level input current	V <sub>I</sub> at GND				-10	μΑ
loo	Short-circuit output current (see Note 6)	V <sub>CC</sub> = 3.6 V,	VO = 0 V		±1 <i>E</i>	±40	mA
los	Short-circuit output current (see Note 6)	V <sub>CC</sub> = 5.5 V,	VO = 0 V		±15	±40	ША
r <sub>O</sub>	Output resistance	$V_{CC} = V_{DD} = V_{SS} = 0 V,$	V <sub>O</sub> = ±2 V	300	500		Ω

 $<sup>^{\</sup>dagger}$  All typical values are at V<sub>CC</sub> = 3.3 V or V<sub>CC</sub> = 5 V, and T<sub>A</sub> = 25°C.

## switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

	PARAMETER	TEST COI	NDITIONS	MIN	TYP†	MAX	UNIT	
	Propagation delay time, low- to high-level output		V <sub>CC</sub> = 3.3 V	100	500	850	20	
tPLH	Propagation delay time, low- to high-level output	$C_L = 50 \text{ pF},$	V <sub>CC</sub> = 5 V	100	500	850	ns	
<b></b>	Propagation delay time, high- to low-level output	$R_L$ = 3 kΩ to 7 kΩ, See Figure 1	V <sub>CC</sub> = 3.3 V	100	500	850	no	
tPHL	Propagation delay time, high- to low-level output		V <sub>CC</sub> = 5 V	100	500	850	ns	
<sup>t</sup> PZH	Output enable time to high level	C <sub>L</sub> = 50 pF,	$R_L = 3 \text{ k}\Omega \text{ to } 7 \text{ k}\Omega,$		1	5	ms	
tPZL	Output enable time to low level	See Figure 2	_		3	7	ms	
4	Output disable time from high level		V <sub>CC</sub> = 3.3 V		0.9	3		
tPHZ	Output disable time nom nign level	C <sub>L</sub> = 50 pF,	V <sub>CC</sub> = 5 V		0.6	3	μs	
4	Output disable time from law lavel	$R_L$ = 3 kΩ to 7 kΩ, See Figure 2	V <sub>CC</sub> = 3.3 V		0.5	3		
tPLZ	Output disable time from low level	J	V <sub>CC</sub> = 5 V		0.3	3	μs	
SR	Slew rate	C <sub>L</sub> = 50 pF, See Figure 1	$R_L = 3 \text{ k}\Omega \text{ to } 7 \text{ k}\Omega,$	4		30	V/μs	
SR(tr)	Slew rate, transition region	C <sub>L</sub> = 2500 pF, See Figure 3	$R_L = 3 \text{ k}\Omega \text{ to } 7 \text{ k}\Omega,$	3		30	V/μs	

<sup>†</sup> All typical values are at  $V_{CC} = 3.3 \text{ V}$  or  $V_{CC} = 5 \text{ V}$ , and  $T_A = 25^{\circ}\text{C}$ .



NOTE 6: Short-circuit durations should be controlled to prevent exceeding the device absolute maximum power dissipation ratings, and not more than one output should be shorted at a time.

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### **RECEIVER SECTION**

# electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

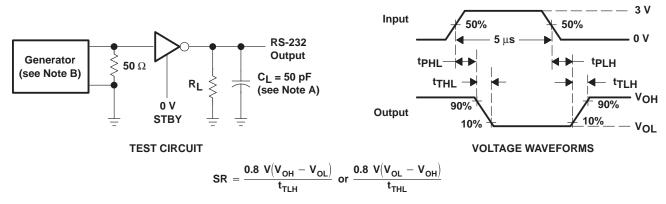
	PARAMETER	TEST COND	DITIONS	MIN	TYP†	MAX	UNIT
V0	High-level output voltage	I <sub>OH</sub> = -2 mA	V <sub>CC</sub> = 3.3 V	2.4	3		V
VOH	riigh-level output voltage	10H = -2 111A	V <sub>CC</sub> = 5 V	3.5	5		٧
VOL	Low-level output voltage	$I_{OL} = 2 \text{ mA}$			0.2	0.4	V
V <sub>IT+</sub>	Positive-going input threshold voltage				2.2	2.6	V
V <sub>IT</sub> –	Negative-going input threshold voltage			0.6	1		V
V <sub>hys</sub>	Input hysteresis (V <sub>IT+</sub> – V <sub>IT</sub> )			0.5	1.2	1.8	V
rį	Input resistance	$V_1 = \pm 3 \text{ V to } \pm 25 \text{ V}$		3	5	7	kΩ

 $<sup>\</sup>dagger$  All typical values are at V<sub>CC</sub> = 3.3 V or V<sub>CC</sub> = 5 V, and T<sub>A</sub> = 25°C.

# switching characteristics over recommended ranges of supply voltage and operating free-air temperature, CL = 50 pF, RL = 3 k $\Omega$ to GND

	PARAMETER	TEST	V <sub>CC</sub> = 3.3 V			V	CC = 5 V	'	UNIT
	PARAMETER	CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
tPLH	Propagation delay time, low- to high-level output		10	70	200	10	70	200	ns
tPHL	Propagation delay time, high- to low-level output	]	10	60	200	10	55	200	ns
<sup>t</sup> PLH	Propagation delay time, low- to high-level output (wake-up mode)	See Figure 4		40	200		40	200	μs
tPHL	Propagation delay time, high- to low-level output (wake-up mode)			90	500		70	500	ns
<sup>t</sup> PZH	Output enable time to high level			3	10		1.2	10	μs
tPZL	Output enable time to low level	See Figure 5		100	250		60	250	ns
tPHZ	Output disable time from high level	See Figure 5	100	200	600	100	150	600	ns
tPLZ	Output disable time from low level	]		130	250		60	250	ns

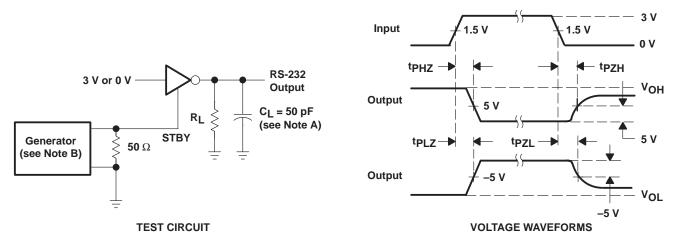
#### PARAMETER MEASUREMENT INFORMATION



NOTES: A.  $C_L$  includes probe and jig capacitance.

B. The pulse generator has the following characteristics:  $Z_0 = 50 \Omega$ , 50% duty cycle,  $t_r \le 10$  ns,  $t_f \le 10$  ns.

Figure 1. Driver Propagation Delay Times and Slew Rate (5-μs Input)

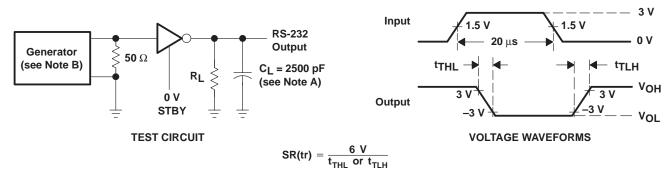


NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

B. The pulse generator has the following characteristics:  $Z_O = 50~\Omega$ , 50% duty cycle,  $t_\Gamma \le 10~\text{ns}$ .

Figure 2. Driver Enable and Disable Test Times

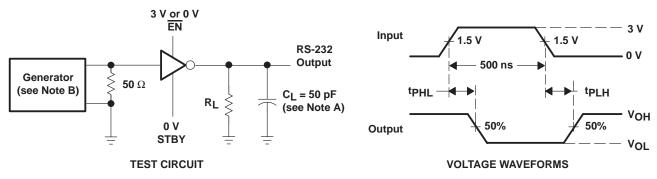
#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

B. The pulse generator has the following characteristics:  $Z_{O} = 50 \Omega$ , 50% duty cycle,  $t_{r} \le 10$  ns,  $t_{f} \le 10$  ns.

Figure 3. Driver Transition Times and Slew Rate (20-µs Input)

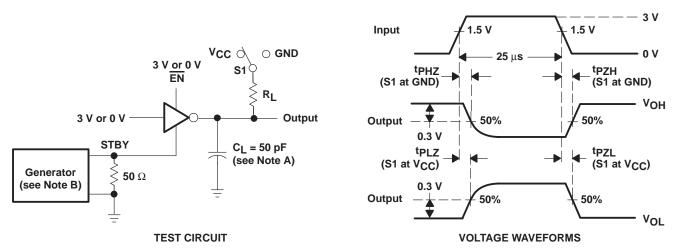


NOTES: A.  $C_L$  includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 1 MHz,  $Z_O = 50~\Omega$ , 50% duty cycle,  $t_\Gamma \le 10~ns$ ,  $t_f \le 10~ns$ .

Figure 4. Receiver Propagation Delay Times

#### PARAMETER MEASUREMENT INFORMATION



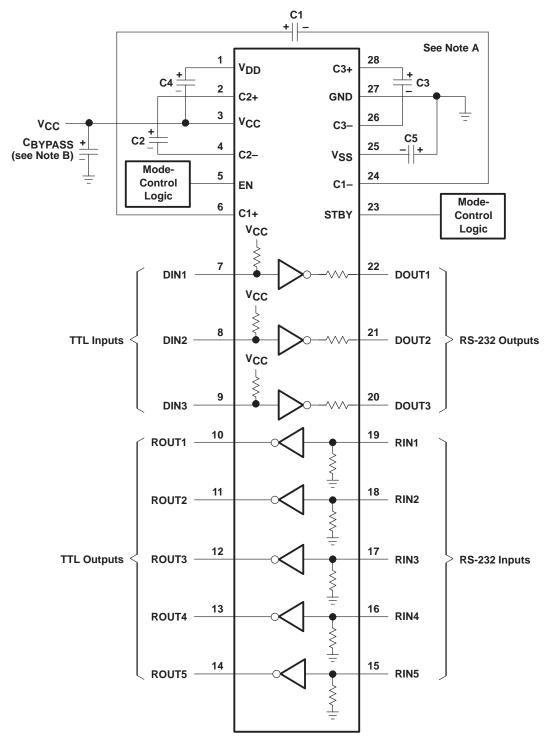
NOTES: A.  $C_L$  includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 1 MHz,  $Z_O = 50~\Omega$ , 50% duty cycle,  $t_\Gamma \le 10~ns$ ,  $t_f \le 10~ns$ .

Figure 5. Receiver Enable and Disable Times



#### **APPLICATION INFORMATION**



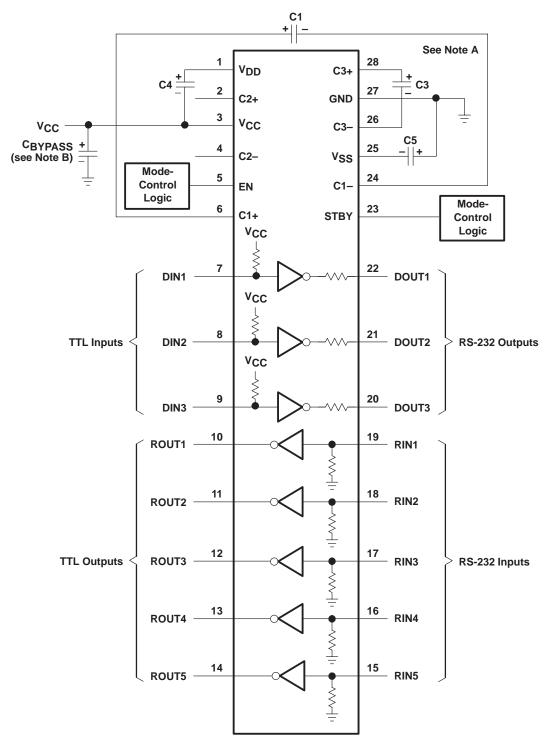
NOTES: A.  $C1 = C2 = C3 = C4 = C5 = C_{BYPASS} = 0.1 \mu F$ 

B. CBYPASS is used as a decoupling capacitor.

Figure 6. Typical 3.3-V Operating Circuit



#### **APPLICATION INFORMATION**



NOTES: A. C2 is not used. C1 = C3 = C4 = C5 = CBYPASS = 0.1  $\mu F$ 

B. CBYPASS is used as a decoupling capacitor.

Figure 7. Typical 5-V Operating Circuit







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#### PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN75LV4737ADB	ACTIVE	SSOP	DB	28	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75LV4737ADBE4	ACTIVE	SSOP	DB	28	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75LV4737ADBG4	ACTIVE	SSOP	DB	28	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75LV4737ADBLE	OBSOLETE	SSOP	DB	28		TBD	Call TI	Call TI
SN75LV4737ADBR	ACTIVE	SSOP	DB	28	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75LV4737ADBRE4	ACTIVE	SSOP	DB	28	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75LV4737ADBRG4	ACTIVE	SSOP	DB	28	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

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NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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### TAPE AND REEL INFORMATION





Α	0	Dimension designed to accommodate the component width
В	0	Dimension designed to accommodate the component length
		Dimension designed to accommodate the component thickness
٧	٧	Overall width of the carrier tape
ГР	1	Pitch between successive cavity centers

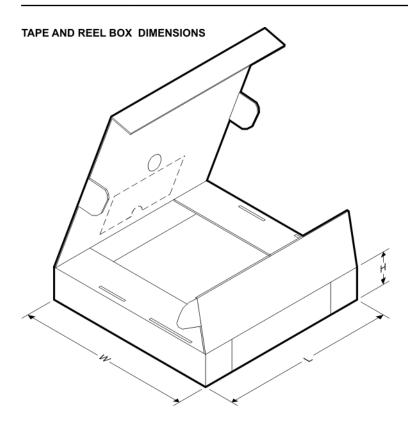
## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75LV4737ADBR	SSOP	DB	28	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1





#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75LV4737ADBR	SSOP	DB	28	2000	346.0	346.0	33.0

## DB (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE

#### **28 PINS SHOWN**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

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